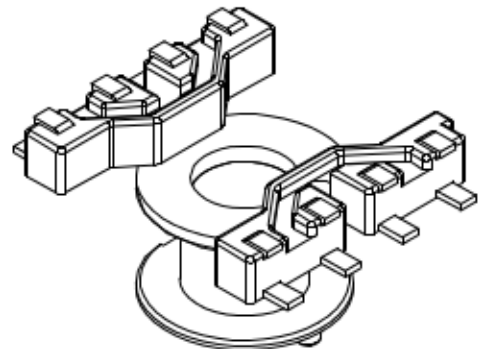
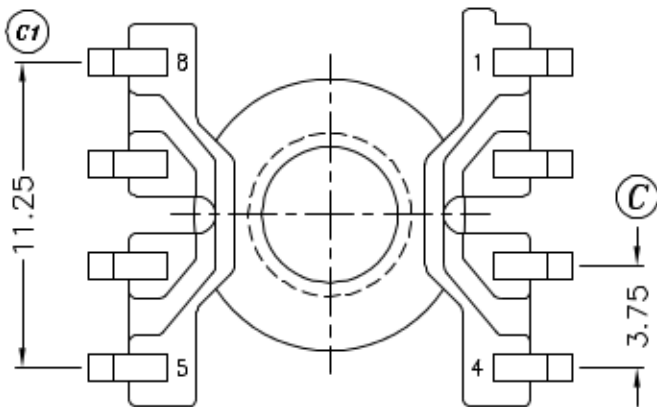


Terminal solder plating :
Sn100%, 5~10 μm



REV.	REVISIONS REC.	DATE	REV.	REVISIONS REC.	DATE
1	CANCEL (P),(O),(B1),(R),(S); ADD (I); UPDATE DRAWING.				

DRAWN & DRAFTED BY ZHANG ZHI QIANG	TOLERANCES		ANGLE: ±1°	TITLE: C TYPE SMD BOBBIN RM-5	
	0<L≤4 ±0.1	pin pitch 0.1 MAX	UNIT: MM	BOBBIN MATERIAL: PHENOLIC PM9630	UL REC. UL 94V-0
CHECKED & APPROVED BY JOHN RONG	4<L≤16 ±0.2		ORIGIN: DG	PIN MATERIAL: PHOSPHOR BRONZE	PIN TENSION LOAD: 1.0KG MIN
LEPCOS (NWL) http://ferrite.ru			DATE: APR.02 '2003	DRAWING NO.	REV.
				S-506	0